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August 28, 2025

For Immediate Release

Company name: SHIBAURA MECHATRONICS

CORPORATION

Name of representative: Keigo Imamura

Representative Director, President and

Chief Executive Officer

(Securities code: 6590; Tokyo Stock Exchange, Prime Market)

Inquiries: Shinji Imai

Vice President, Executive General Manager

of Corporate Management Division (Telephone: +81-45-897-2425)

Notice Regarding Capital and Business Alliance with Photo electron Soul Inc. and Undertaking of Third-Party Allotment of Shares

Shibaura Mechatronics Corporation (hereinafter referred to as the "Company") hereby announces that it has agreed to enter into a capital and business alliance with Photo electron Soul Inc. (hereinafter referred to as "PeS") for a semiconductor photocathode e-beam system that PeS has developed (hereinafter referred to as the "E-beam System"), and to undertake new stocks that PeS will issue as the third-party allotment of shares as described below.

1. Reason for the capital and business alliance

The Company set forth "Contributing to prosperous lives with excellent technologies and services." as its management policy. Based on this policy, the Company formulated its long-term vision "Shibaura Vision 2033," in which the Company defines "a corporate group which comprehends future issues of society and customers and the potential needs that exist there, makes suggestions and gives solutions actively, and achieves growth with customers" as the state the Company outlines to achieve in 10 years, namely in 2033. At the same time, the Company is aiming to achieve performance targets of 100 billion yen or more in consolidated net sales and ROS of 20% or higher within the vision period.

Furthermore, with the SPE field as the core of its business portfolio, the Company is focusing on the continued expansion of the Company's development, manufacturing, sales, and maintenance service businesses for front and back-end process equipment for semiconductors, particularly for products for advanced fields. Besides, the Company actively considers entering new businesses with the aim of achieving growth over the vision period.

On the other hand, PeS views the growing needs for e-beam-based inspection and analysis as a business opportunity. By providing the E-beam System based on its unique e-beam technologies, PeS is striving to create value unattainable with conventional e-beam technologies, while also being expected to deliver mass-produced products more rapidly.

Against this backdrop, it has led to the agreement on this alliance — the expected business synergies arising from PeS's aim of promptly strengthening of the framework for providing the E-beam System and the Company's technologies and expertise in semiconductor manufacturing equipment, and further from the shared future vision of both companies to contribute to solving social issues through new technologies. Through this alliance, the Company aims to contribute to solving social issues and further increase its corporate value in the medium to long term.

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(Reference)

Inspection and analysis of defects and structures in semiconductor devices are essential for the rapid improvement of yield, and the inspection and analysis methods are broadly categorized into optical methods and electron beam methods. With the recent progress in miniaturization and multilayering of semiconductor devices, inspection and analysis at the nano level, which is extremely fine, have become indispensable. In this context, the necessity of e-beam methods, which allow detection at even finer levels than optical methods, is increasing.

The E-beam System is a new type of system for industrial-use of e-beam generation sources and represents the first method in around half a century.

By using the E-beam System, without moving the axis from which the beam is emitted, the intensity can be instantaneously controlled, and the e-beam can be irradiated to the target (selective e-beam irradiation technology). As a result, it becomes possible to inspect and analyze device structures that were previously invisible — such as the bottoms and deep areas of deep holes and deep trenches — without damaging the target, to discover and analyze defects, and to perform non-contact inspection and analysis of the electrical characteristics of miniature transistors.

2. Content of the capital and business alliance

(1) Content of the business alliance

The Company and PeS will have a business alliance regarding the manufacturing and maintenance services for the E-beam System. The details regarding the methods and content of the business alliance will be proceeded with continuous discussions. Shibaura Eletec Corporation, one of the subsidiaries of the Company, will also participate in the maintenance business for the E-beam System.

(2) Content of the capital alliance

The Company will undertake some part of one billion yen that PeS newly plans to raise.

3. Overview of the counterparty in the capital and business alliance (as of June 30, 2025)

(1)	Name	Photo electron Soul Inc.			
(2)	Location	NALIC, 2-22-8 Chikusa, Chikusa-ku, Nagoya, Aichi, Japan			
(3)	Job title and name of representative	Takayuki Suzuki, Chief Executive Officer, ph.D.			
(4)	Description of business	Research, development, manufacturing and sales of semiconductor photocathode e-beam system			
(5)	Share capital	100 million yen			
(6)	Date of establishment	July 1, 2015			
(7)	Relationship between the Company and said company	Capital relationship	Not applicable		
		Personnel relationship	Not applicable		
		Business relationship	Not applicable		
		Related party relationship	Not applicable		

(Note) Major shareholders and ownership ratios, and operating results and financial positions of said company for the last three years are not disclosed at the said party's request.

4. Schedule

(1) Date of resolution at a meeting of the Board of Directors August 28, 2025

(2) Date of conclusion of related agreements August 29, 2025 (scheduled)

(3) Due date of payment September 25, 2025 (scheduled)

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5. Impact on financial results

The Company believes that this alliance will contribute to the enhancement of the Company's corporate value over the medium- to long-term. The Company, however, anticipates that the impact of this alliance on its consolidated financial results for the fiscal year ending March 31, 2026, will be minimal. If any matter that must be disclosed arises, information about the matter shall be immediately disclosed.

(Reference) Consolidated financial results forecasts for the current fiscal year (released on May 14, 2025) and actual consolidated results for the previous fiscal year

(Unit: million yen)

	Net sales	Operating income	Ordinary income	Net income attributable to owners of parent
Consolidated financial results forecasts for the current fiscal year (Fiscal year ending March 31, 2026)	80,000	10,500	10,100	7,500
Actual consolidated results for the previous fiscal year (Fiscal year ended March 31,2025)	80,915	14,135	13,977	10,328

(Note) The forward-looking statements including results forecasts contained in these materials are based on information currently available to the Company at the time of the release of these materials. Actual results may differ from the above forecasts due to a range of factors going forward.